

Product Summary

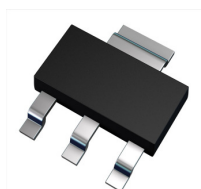
$V_{(BR)DSS}$	$R_{DS(on)}$	I_D $T_A = +25^\circ\text{C}$
-100V	350mΩ @ $V_{GS} = -10\text{V}$	-2.4A
	450mΩ @ $V_{GS} = -6\text{V}$	-2.1A

Description and Applications

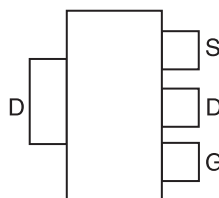
This MOSFET is designed to minimize the on-state resistance and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Motor Control
- DC-DC Converters
- Power Management Functions
- Relay and Solenoid Driving

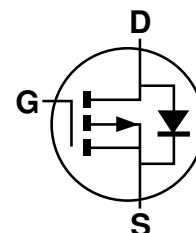
SOT223



Top View



Pin Out - Top



Equivalent Circuit

Features and Benefits

- Fast Switching Speed
- Low Input Capacitance
- Low Gate Drive
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

Mechanical Data

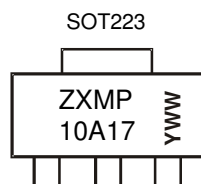
- Case: SOT223
- Case Material: Molded Plastic; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin Annealed over Copper Leadframe; Solderable per MIL-STD-202, Method 208 ③
- Weight: 0.112 grams (Approximate)

Ordering Information (Note 4)

Product	Case	Packaging
ZXMP10A17GTA	SOT223	1,000/Tape & Reel

- Notes:
1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information



ZXMP 10A17 = Product Type Marking Code
 YWW = Date Code Marking
 Y or $\bar{Y}$ = Last Digit of Year (ex: 5= 2015)
 WW or $\bar{WW}$ = Week Code (01~53)

Maximum Ratings (@T_A = +25°C unless otherwise specified.)

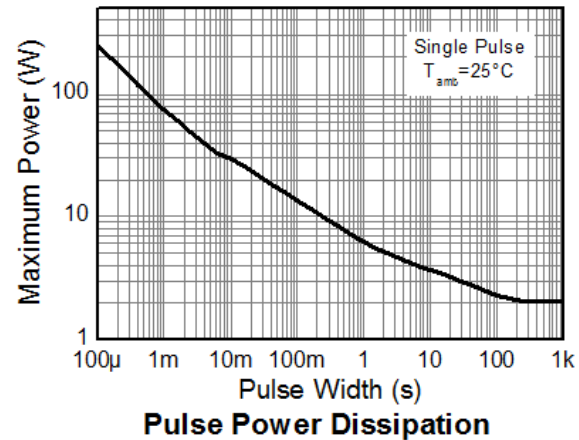
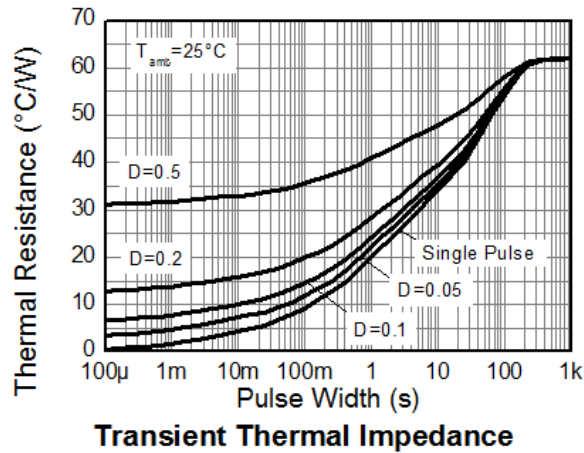
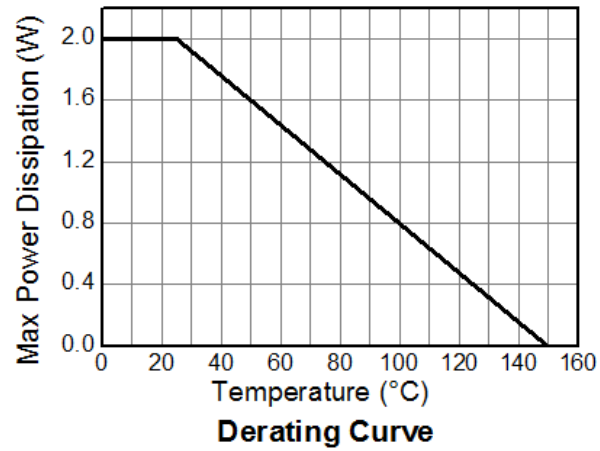
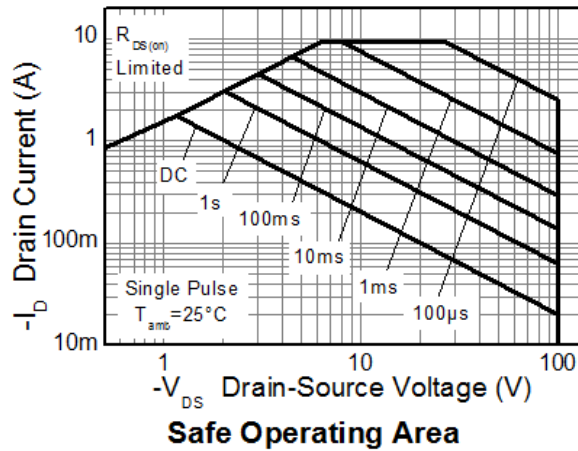
Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V _{DSS}	-100	V
Gate-Source Voltage			V _{GS}	±20	V
Continuous Drain Current	V _{GS} = 10V	(Note 6)	I _D	-2.4	A
		T _A = +70°C (Note 6)		-1.9	
		(Note 5)		-1.7	
Pulsed Drain Current	V _{GS} = 10V	(Note 7)	I _{DM}	-9.4	A
Continuous Source Current (Body Diode)		(Note 6)	I _S	-4.5	A
Pulsed Source Current (Body Diode)		(Note 7)	I _{SM}	-9.4	A

Thermal Characteristics (@T_A = +25°C unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Power Dissipation Linear Derating Factor	(Note 5)	P _D	2.0	W mW/°C
			16	
	(Note 6)		3.9 31	
Thermal Resistance, Junction to Ambient	(Note 5)	R _{θJA}	62.5	°C/W
	(Note 6)		32.0	
Thermal Resistance, Junction to Case	(Note 8)	R _{θJL}	9.8	
Operating and storage temperature range		T _J , T _{STG}	-55 to 150	°C

- Notes:
5. For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
 6. Same as Note 5, except the device is measured at t ≤ 10 seconds.
 7. Same as Note 5, except the device is pulsed with D = 0.02 and pulse width 300 μs. The pulse current is limited by the maximum junction temperature.
 8. Thermal resistance from junction to solder-point (at the end of the drain lead).

Thermal Characteristics

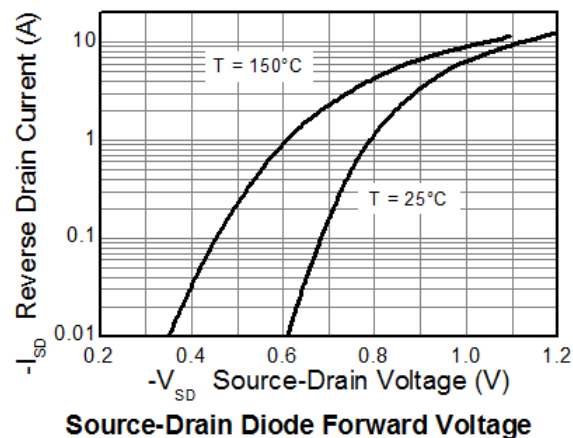
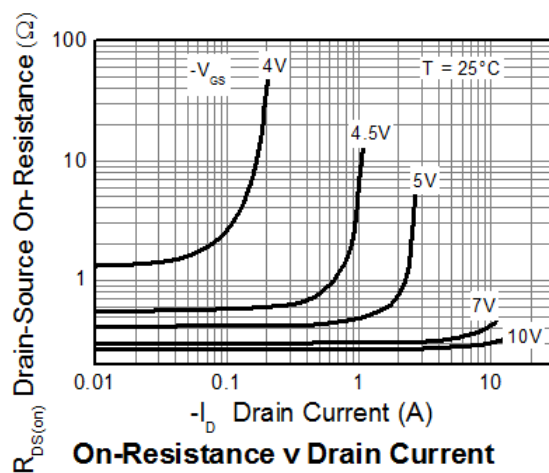
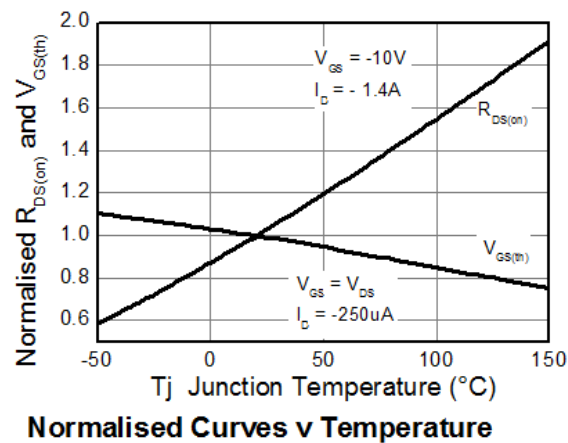
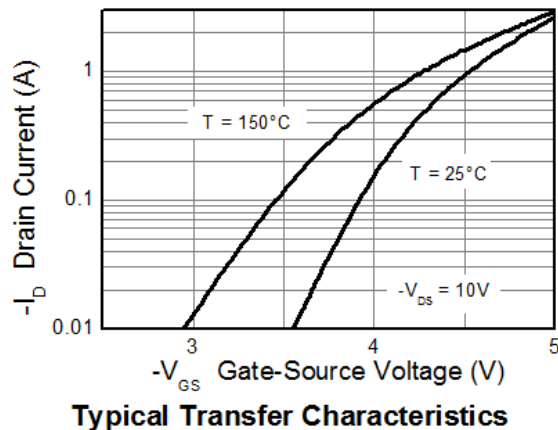
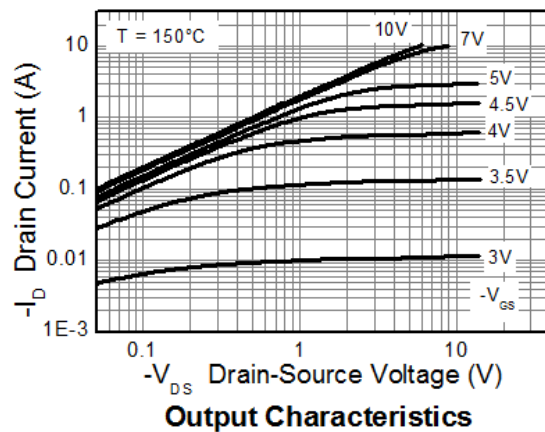
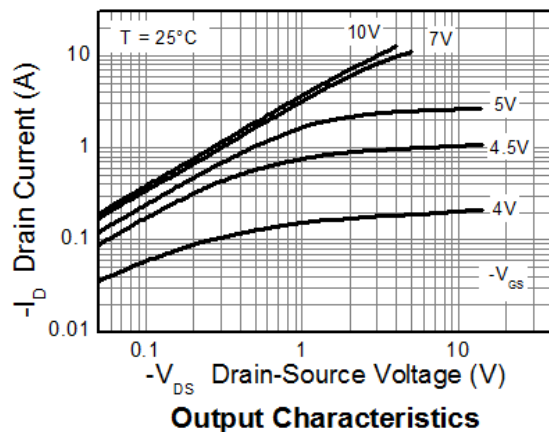


Electrical Characteristics (@T_A = +25 °C unless otherwise specified.)

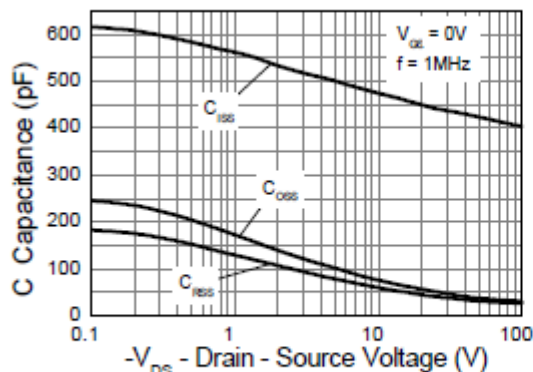
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition	
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage	BV _{DSS}	-100	—	—	V	I _D = -250μA, V _{GS} = 0V	
Zero Gate Voltage Drain Current	I _{DSS}	—	—	-0.5	μA	V _{DS} = -100V, V _{GS} = 0V	
Gate-Source Leakage	I _{GSS}	—	—	±100	nA	V _{GS} = ±20V, V _{DS} = 0V	
ON CHARACTERISTICS							
Gate Threshold Voltage	V _{GS(th)}	-2.0	—	-4.0	V	I _D = -250μA, V _{DS} = V _{GS}	
Static Drain-Source On-Resistance (Note 9)	R _{DS (ON)}	—	—	0.350	Ω	V _{GS} = -10V, I _D = -1.4A	
				0.450		V _{GS} = -6V, I _D = -1.2A	
Forward Transconductance (Notes 9 & 10)	g _{fs}	—	2.8	—	S	V _{DS} = -15V, I _D = -1.4A	
Diode Forward Voltage (Note 9)	V _{SD}	—	-0.85	-0.95	V	I _S = -1.7A, V _{GS} = 0V	
Reverse Recovery Time (Note 10)	t _{rr}	—	33	—	ns	I _F = -1.5A, di/dt= 100A/μs	
Reverse Recovery Charge (Note 10)	Q _{rr}	—	48	—	nC		
DYNAMIC CHARACTERISTICS (Note 10)							
Input Capacitance	C _{iss}	—	424	—	pF	V _{DS} = -50V, V _{GS} = 0V f= 1MHz	
Output Capacitance	C _{oss}	—	36.6	—	pF		
Reverse Transfer Capacitance	C _{rss}	—	29.8	—	pF		
Total Gate Charge (Note 11)	Q _g	—	7.1	—	nC	V _{GS} = -6.0V	V _{DS} = -50V I _D = -1.4A
Total Gate Charge (Note 11)	Q _g	—	10.7	—	nC	V _{GS} = -10V	
Gate-Source Charge (Note 11)	Q _{gs}	—	1.7	—	nC		
Gate-Drain Charge (Note 11)	Q _{gd}	—	3.8	—	nC		
Turn-On Delay Time (Note 11)	t _{D(on)}	—	3.0	—	ns	V _{DD} = -15V, V _{GS} = -10V I _D = -1A, R _G ≅ 6.0Ω	
Turn-On Rise Time (Note 11)	t _r	—	3.5	—	ns		
Turn-Off Delay Time (Note 11)	t _{D(off)}	—	13.4	—	ns		
Turn-Off Fall Time (Note 11)	t _f	—	7.2	—	ns		

Notes: 9. Measured under pulsed conditions. Pulse width ≤ 300μs; duty cycle ≤ 2%.
 10. For design aid only, not subject to production testing.
 11. Switching characteristics are independent of operating junction temperatures.

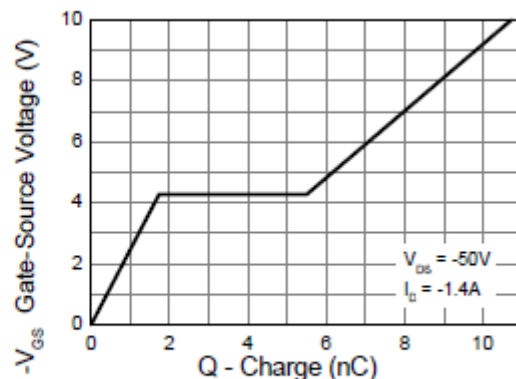
Typical Characteristics



Typical Characteristics (cont.)

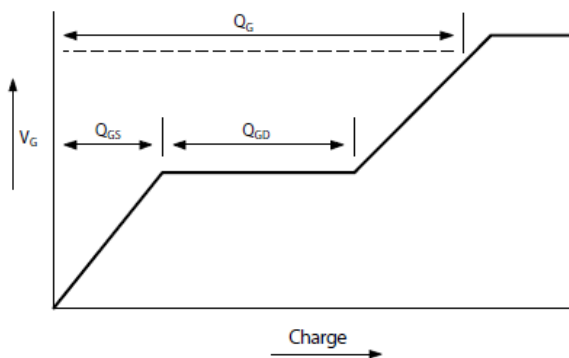


Capacitance v Drain-Source Voltage

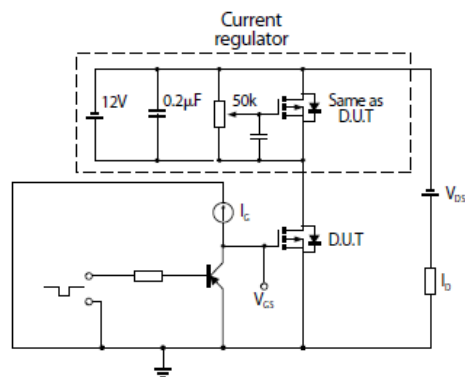


Gate-Source Voltage v Gate Charge

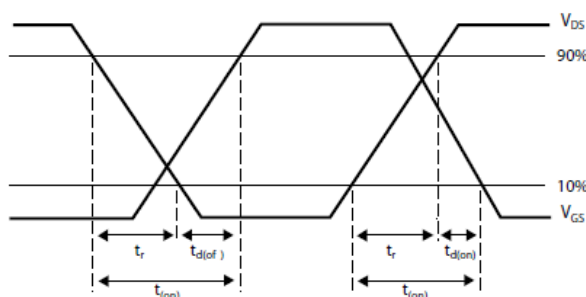
Test Circuits



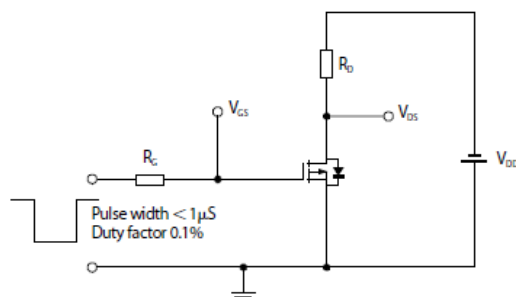
Basic gate charge waveform



Gate charge test circuit



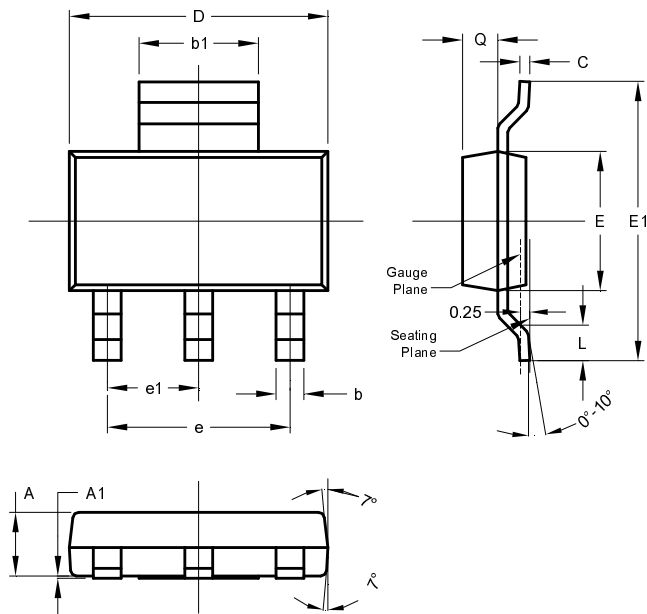
Switching time waveforms



Switching time test circuit

Package Outline Dimensions

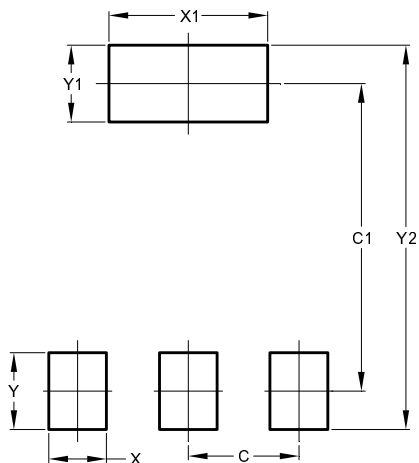
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



SOT223			
Dim	Min	Max	Typ
A	1.55	1.65	1.60
A1	0.010	0.15	0.05
b	0.60	0.80	0.70
b1	2.90	3.10	3.00
C	0.20	0.30	0.25
D	6.45	6.55	6.50
E	3.45	3.55	3.50
E1	6.90	7.10	7.00
e	-	-	4.60
e1	-	-	2.30
L	0.85	1.05	0.95
Q	0.84	0.94	0.89
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
C	2.30
C1	6.40
X	1.20
X1	3.30
Y	1.60
Y1	1.60
Y2	8.00

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